

## Amendments to the Claims:

1 (currently amended): A hot melt adhesive that can be applied to a substrate at a temperature of less than about 110°C, said adhesive comprising an

ethylene n-butyl acrylate as the only ethylene copolymer present in said adhesive,

a paraffin wax,

a rosin derived tackifier and

an aromatic tackifier.

2 (original): The adhesive of claim 1 that can be applied to a substrate at a temperature of from about 80°C to a temperature of about 100°C.

3 (original): The adhesive of claim 2 that can be applied to a substrate at a temperature of from about 80°C to a temperature of about 90°C.

4 (canceled)

5 (currently amended): The adhesive of claim 1 comprising from about 20 to about 40 wt % of said ethylene n-butyl acrylate, from about 20 to about 40 wt % of said wax, from about 5 to about 30 wt % of an aromatic tackifier, and from about 2 to about 40 wt % a rosin tackifier .

6 (original): An article of manufacture comprising the adhesive of claim 1.

7 (original): The article of claim 6 which is a carton or carton, case, tray or bag.

8 (original): A method of sealing and/or forming a case, carton, tray or bag comprising applying the hot melt adhesive of claim 1 to seal and/or form the case, carton, tray, or bag.

9 (original): A packaged article contained within a carton, case, tray or bag, wherein the carton, case, tray or bag comprises the adhesive of claim 1.

10 (canceled)

11 (currently amended): The packaged article of claim 9-12 which is a packaged frozen food article.

12 (original): A process for bonding a substrate to a similar or dissimilar substrate comprising applying to at least one substrate a molten hot melt adhesive composition and bonding said substrate together, said hot melt adhesive comprising the adhesive of claim 1, wherein the adhesive is applied at a temperature of less than about 100 °C

13 (original): The process of claim 12 wherein the adhesive is applied at a temperature of about 80°C to about 90°C.